

## **LOWER ELECTRODE DESIGN FOR HIGHER UNIFORMITY**

### **Abstract of the Disclosure**

5           A plasma processing system for processing a substrate is disclosed. The  
plasma processing system includes a process chamber within which a plasma is both  
ignited and sustained for processing. The plasma processing system further includes  
an electrode disposed at the lower end of the process chamber. The electrode is  
configured for generating an electric field inside the process chamber. The plasma  
10       processing system also includes a component for controlling an impedance between  
the electrode and the plasma. The impedance is arranged to affect the electric field to  
improve processing uniformity across the surface of the substrate.

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